



Material Content Data Sheet



Sales Product Name		BSC042N03LS G		Issued		22. January 2018		
MA#		MA000441380						
Package		PG-TDSON-8-5		Weight*		119.12 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.426	1.20	1.20	11974	11974
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		317	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.71	31.75	317009	317421
wire	non noble metal	copper	7440-50-8	0.048	0.04	0.04	400	400
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		721	
	plastics	epoxy resin	-	6.102	5.12		51226	
	inorganic material	silicondioxide	60676-86-0	36.784	30.88	36.07	308800	360747
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12186	12186
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1390	1390
solder	non noble metal	tin	7440-31-5	0.032	0.03		267	
	noble metal	silver	7440-22-4	0.040	0.03		334	
	non noble metal	lead	7439-92-1	1.518	1.27	1.33	12747	13348
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.50	9.51	95031	95155
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		187	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.71	18.74	187136	187379
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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